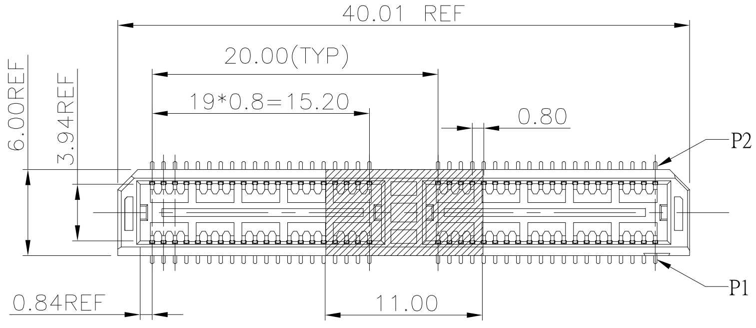
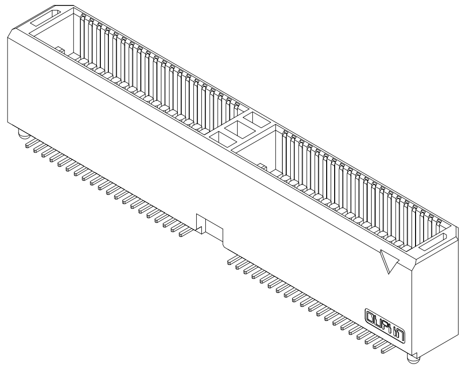
REV.	SPECIFICATION	ECN NO.	APPD.
R3		ECN220301	





Material and Plating:

Housing: LCP, UL94V-0 , Black.

Signal Contacts :Brass.

Gold Plated on Contact Area and 80u" Min Tin Plated on Solder Tail over nickel 50u" Min .

Electrical Characteristics:

Current Rating: 2A .

Voltage Rating: 125V AC .

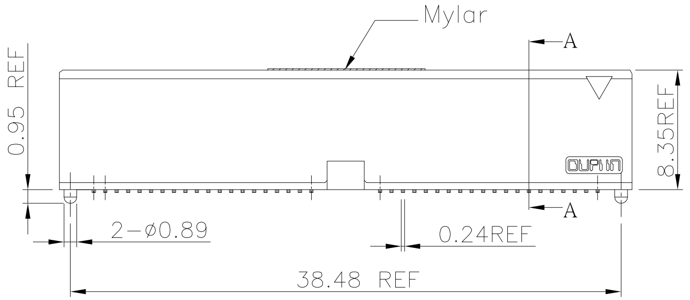
Dielectric Withstanding Voltage: 525V AC For 1 minute.

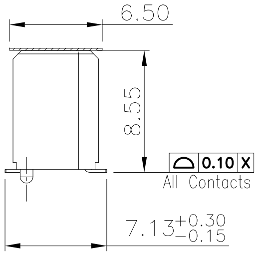
Insulator Resistance: 5000MΩ min at DC 500V.

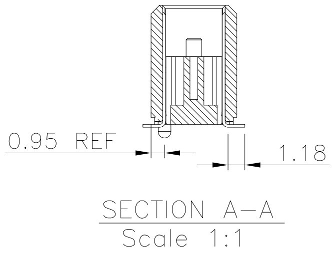
Contact Resistance: Signal Pin: 45mΩ max .

Operating Temperature: -55°C ~ +125°C .

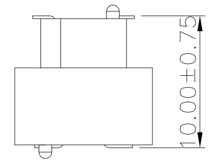
***RoHS Compliant**



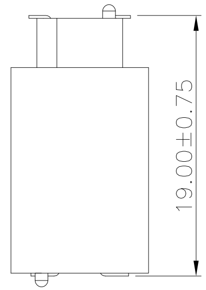




SECTION A-A
Scale 1:1



Mating With Female:
2337-80FC2DP1T-S



Mating With Female:
2337-80FC2DP2T-S

Mating Height

2337- 80 M C 2 D P 2 T -S

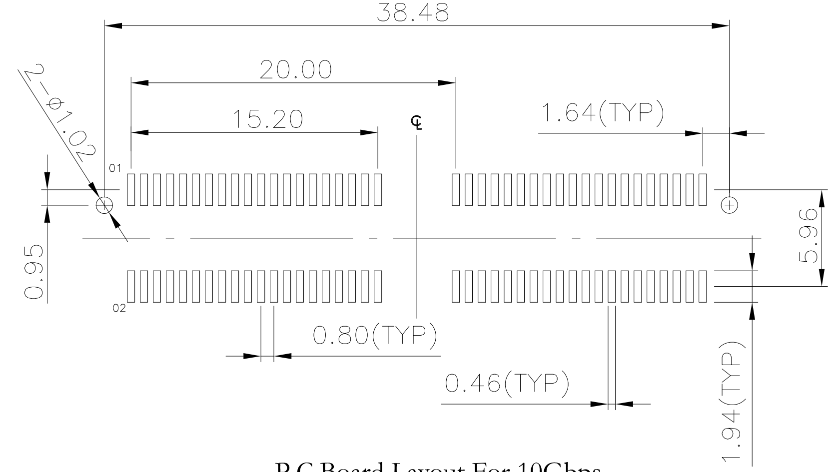
- Series: 2337-
- Position: 80
- M: Male
- C: Selective Gold Plated
- 1: G/F
- 2: 5μ"
- 3: 10μ"
- 7: 30μ"
- D: SMD Type
- N: W/O Post, W/O Lock
- P: With Post, W/O Lock
- L: W/O Post, With Lock
- 2: Code 2 height 8.55mm
- T: Tape & Reel Package
- S: Mylar

Tolerances	Dwg No.		2337-D0000-004		Title:
x. = ±0.50	Projection		⊕ ◁		2337 Series
.x = ±0.25	Unit	mm	Scale	1:1	High Speed Board to Board
.xx = ±0.15	Drawn By		WP 03/01'22		Pitch 0.8mm (Plug)

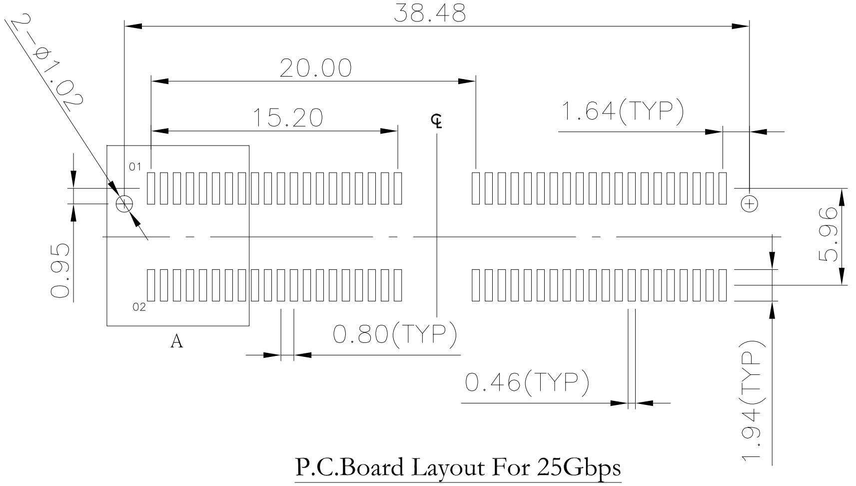
OUPIIN ELECTRONIC(KUNSHAN) CO., LTD.

P/N:	2337-80MC2DP2T-S		
SHEET	1/2	Ver.No.	R3

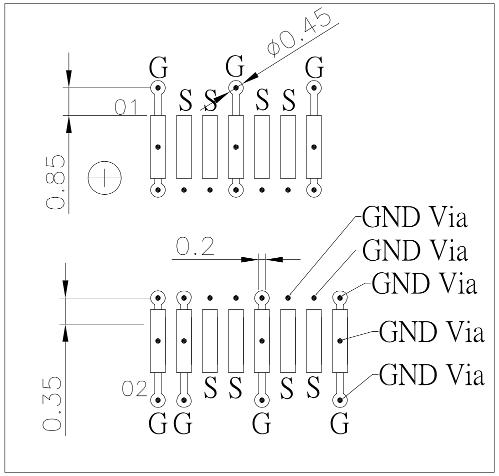
REV.	SPECIFICATION	ECN NO.	APPD.
R3		ECN220301	



P.C.Board Layout For 10Gbps
(Tolerance:±0.05)



P.C.Board Layout For 25Gbps
(Tolerance:±0.05)



Detail A
Sacle2:1

Tolerances	Dwg No.	2337-D0000-004		Title:	
x. = ±0.50	Projection			2337 Series	OUPIIN ELECTRONIC(KUNSHAN) CO., LTD.
.x = ±0.25	Unit *mm*	Scale	1:1	High Speed Board to Board	P/N: 2337-80MC2DP2T-S
.xx = ±0.15	Drawn By	WP 03/01'22		Pitch 0.8mm (Plug)	SHEET 2/2 Ver.No. R3